

# HiPerFET™ Power MOSFET

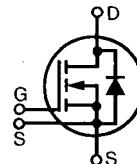
Single MOSFET Die

Preliminary data sheet

## IXFN 180N10

$V_{DSS}$  = 100 V  
 $I_{D25}$  = 180 A  
 $R_{DS(on)}$  = 8 mΩ

$t_{rr} \leq 250$  ns



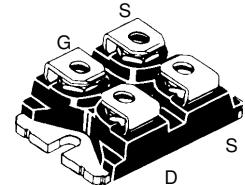
### Symbol Test Conditions

$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	100	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ , $R_{GS} = 1\text{ M}\Omega$	100	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_c = 25^\circ\text{C}$	180	A
$I_{L(RMS)}$	Terminal (current limit)	100	A
$I_{DM}$	$T_c = 25^\circ\text{C}$ ; Note 1	720	A
$I_{AR}$	$T_c = 25^\circ\text{C}$	180	A
$E_{AR}$	$T_c = 25^\circ\text{C}$	60	mJ
$E_{AS}$	$T_c = 25^\circ\text{C}$	3	J
$dv/dt$	$I_S \leq I_{DM}$ , $di/dt \leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ $T_J \leq 150^\circ\text{C}$ , $R_G = 2 \Omega$	5	V/ns
$P_D$	$T_c = 25^\circ\text{C}$	600	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	1.6 mm (0.063 in) from case for 10 s	300	$^\circ\text{C}$
$V_{ISOL}$	50/60 Hz, RMS $t = 1 \text{ min}$ $I_{ISOL} \leq 1 \text{ mA}$ $t = 1 \text{ s}$	2500 3000	V~
$M_d$	Mounting torque Terminal connection torque	1.5/13 Nm/lb.in. 1.5/13 Nm/lb.in.	
<b>Weight</b>		30	g

### Symbol Test Conditions ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
$V_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 3 \text{ mA}$	100		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 8 \text{ mA}$	2		V
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}$ , $V_{GS} = 0 \text{ V}$		$\pm 100$	nA
$I_{DSS}$	$V_{DS} = V_{DSS}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	100 2	$\mu\text{A}$ mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$ , $I_D = 0.5 \cdot I_{D25}$ Note 2		8	mΩ

miniBLOC, SOT-227 B (IXFN)  
 E153432



G = Gate      D = Drain  
S = Source

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

### Features

- International standard package
- Encapsulating epoxy meets UL 94 V-0, flammability classification
- miniBLOC with Aluminium nitride isolation
- Low  $R_{DS(on)}$  HDMOST™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic Rectifier

### Applications

- DC-DC converters
- Synchronous rectification
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls
- Low voltage relays

### Advantages

- Easy to mount
- Space savings
- High power density

**Symbol      Test Conditions**  
 $(T_J = 25^\circ\text{C}$ , unless otherwise specified)

		Characteristic Values		
		Min.	Typ.	Max.
$I_{fs}$	$V_{DS} = 10 \text{ V}; I_D = 60 \text{ A}$ , Note 2	60	90	S
$C_{iss}$		9100		pF
$C_{oss}$	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	3200		pF
$C_{rss}$		1600		pF
$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1 \Omega$ (External),	50		ns
$t_r$		90		ns
$t_{d(off)}$		140		ns
$t_f$		65		ns
$Q_{g(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	360		nC
$Q_{gs}$		65		nC
$Q_{gd}$		190		nC
$R_{thJC}$	LOC, SOT-227 B		0.21	K/W
$R_{thCK}$	miniBLOC, SOT-227 B	0.05		K/W

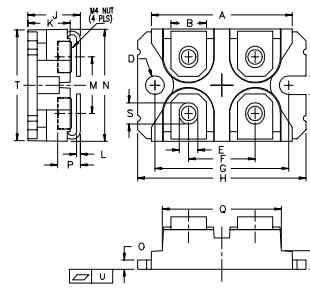
### Source-Drain Diode

$(T_J = 25^\circ\text{C}$ , unless otherwise specified)  
**Symbol      Test Conditions**

		Characteristic Values		
		Min.	Typ.	Max.
$I_s$	$V_{GS} = 0$		180	A
$I_{sm}$	Repetitive; pulse width limited by $T_{JM}$		720	A
$V_{SD}$	$I_F = 100 \text{ A}, V_{GS} = 0 \text{ V}$ , Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2 \%$		1.5	V
$t_{rr}$	$I_F = 50 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}, V_R = 50 \text{ V}$	1.1	250	ns
$Q_{RM}$		13		$\mu\text{C}$
$I_{RM}$				A

- Notes:
1. Pulse width limited by  $T_{JM}$ .
  2. Pulse test,  $t \leq 300 \text{ ms}$ , duty cycle  $d \leq 2 \%$

### miniBLOC, SOT-227 B



M4 screws (4x) supplied

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	38.00	38.23	1.496	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004

Figure 1. Output Characteristics at 25°C

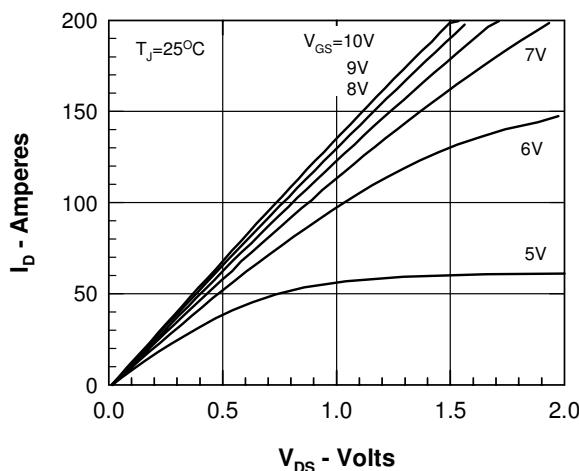
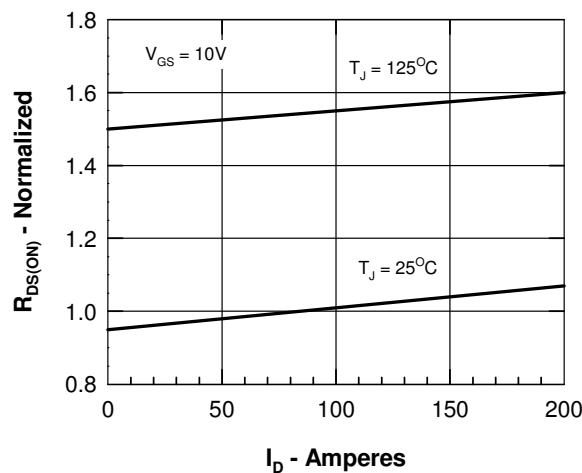
Figure 3.  $R_{DS(on)}$  normalized to 15A/25°C vs.  $I_D$ 

Figure 5. Drain Current vs. Case Temperature

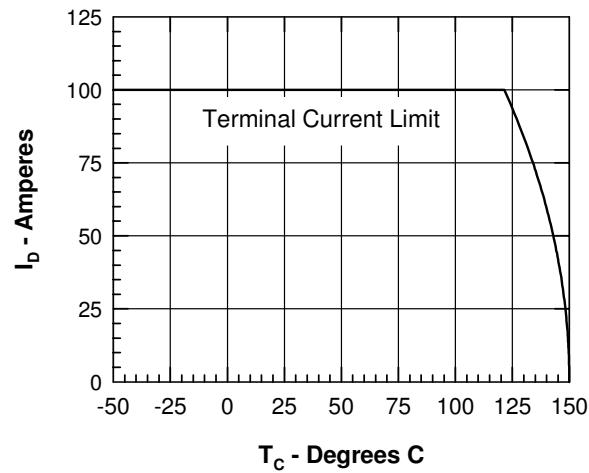


Figure 2. Output Characteristics at 125°C

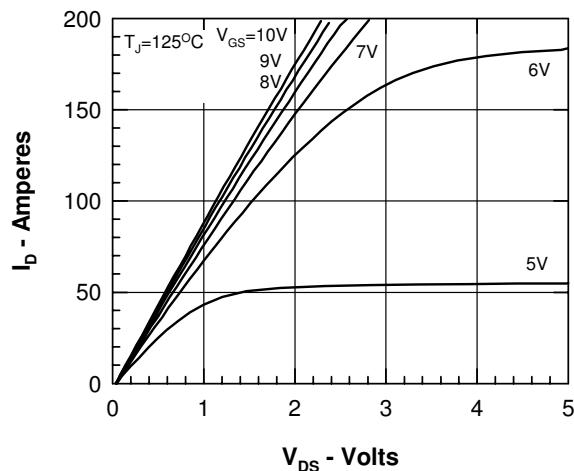
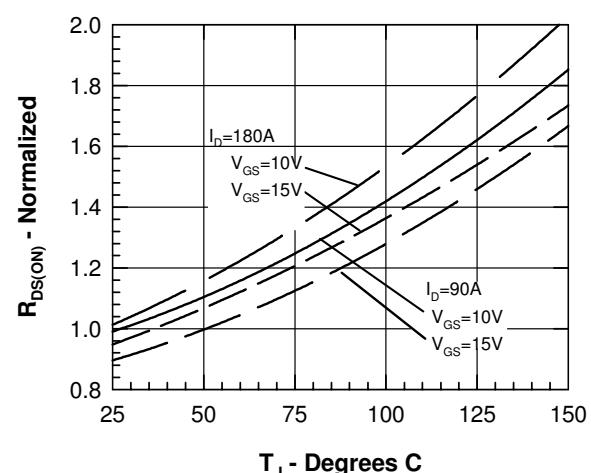
Figure 4.  $R_{DS(on)}$  normalized to 15A/25°C vs.  $T_J$ 

Figure 6. Admittance Curves

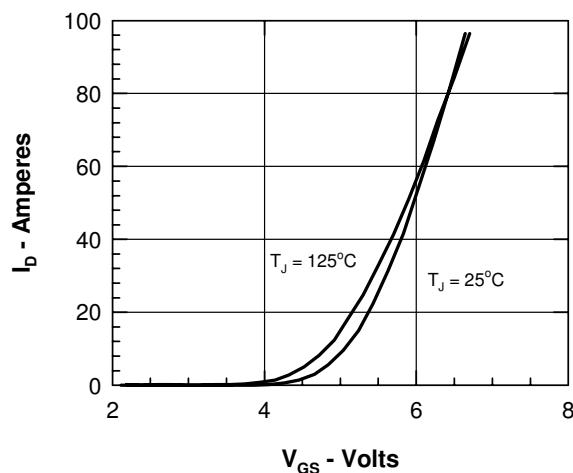


Figure 7. Gate Charge

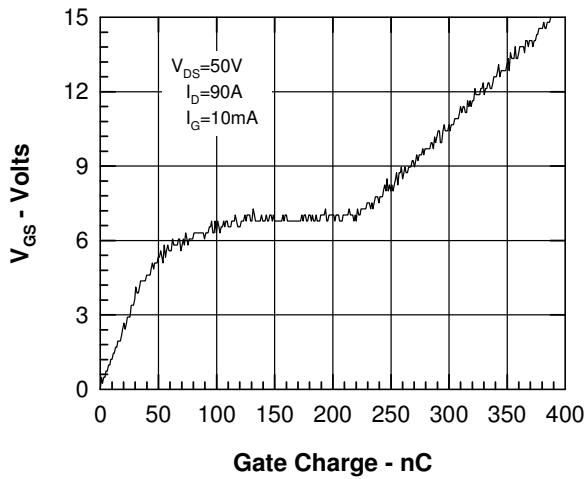


Figure 8. Capacitance Curves

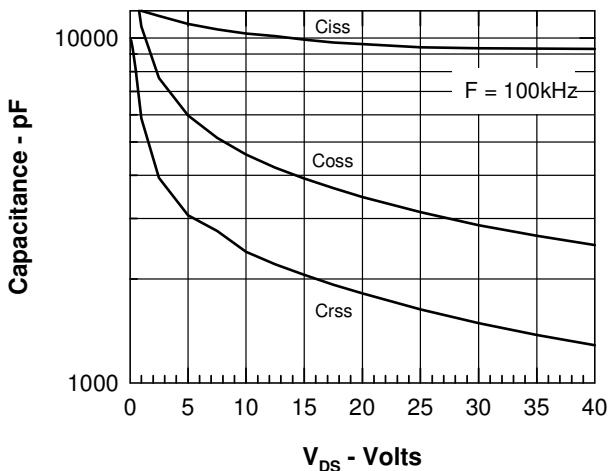


Figure 9. Forward Voltage Drop of the Intrinsic Diode

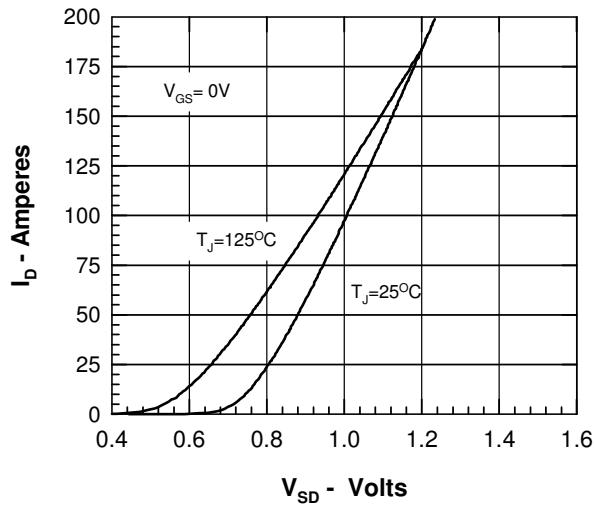


Figure 10. Forward Bias Safe Operating Area

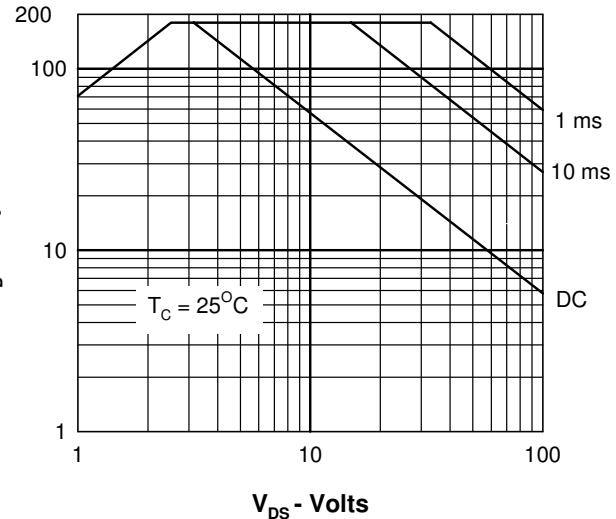


Figure 11. Transient Thermal Resistance

